

## Connection Diagrams




Logic Diagram


Truth Table

| Inputs |  | Outputs |
| :---: | :---: | :---: |
| Dn | $\overline{\text { OEN }}$ | Qn |
| L | L | L |
| H | L | H |
| X | H | Cutoff |

H = HIGH Voltage Level
L = LOW Voltage Level
Cutoff = Lower-than-LOW State
X = Don't Care

Absolute Maximum Ratings (Note 1)
If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.
Above which the useful life may be impaired
Storage Temperature ( $\mathrm{T}_{\text {STG }}$ )
$-65^{\circ} \mathrm{C}$ to $+150^{\circ} \mathrm{C}$
Maximum Junction Temperature ( $\mathrm{T}_{\mathrm{J}}$ )
Ceramic
$+175^{\circ} \mathrm{C}$
$V_{\text {EE }}$ Pin Potential to
Ground Pin
-7.0 V to +0.5 V
Input Voltage (DC)
$\mathrm{V}_{\mathrm{EE}}$ to +0.5 V
$-100 \mathrm{~mA}$
Output Current (DC Output HIGH)
$\geq 2000 \mathrm{~V}$

## Recommended Operating Conditions

Case Temperature ( $\mathrm{T}_{\mathrm{C}}$ )
Military
$-55^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$
Supply Voltage ( $\mathrm{V}_{\mathrm{EE}}$ ) -5.7 V to -4.2 V
Note 1: Absolute maximum ratings are those values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.
Note 2: ESD testing conforms to MIL-STD-883, Method 3015.

## Military Version

## DC Electrical Characteristics

$\mathrm{V}_{\mathrm{EE}}=-4.2 \mathrm{~V}$ to $-5.7 \mathrm{~V}, \mathrm{~V}_{\mathrm{CC}}=\mathrm{V}_{\mathrm{CCA}}=\mathrm{GND}, \mathrm{T}_{\mathrm{C}}=-55^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$

| Symbol | Parameter | Min | Max | Units | $\mathrm{T}_{\mathrm{c}}$ | Conditions |  | Notes |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{OH}}$ | Output HIGH Voltage | -1025 | -870 | mV | $0^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$ | $\begin{aligned} & \mathrm{V}_{\text {IN }}=\mathrm{V}_{\mathrm{IH}(\text { Max })} \\ & \text { or } \mathrm{V}_{\mathrm{IL}(\text { Min })} \end{aligned}$ | Loading with $25 \Omega$ to -2.0V | (Notes 3, 4, 5) |
|  |  | -1085 | -870 | mV | $-55^{\circ} \mathrm{C}$ |  |  |  |
| $\mathrm{V}_{\mathrm{OL}}$ | Output LOW Voltage | -1830 | -1620 | mV | $0^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$ |  |  |  |
|  |  | -1830 | -1555 | mV | $-55^{\circ} \mathrm{C}$ |  |  |  |
| $\mathrm{V}_{\mathrm{OHC}}$ | Output HIGH Voltage | -1035 |  | mV | $0^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$ | $\begin{array}{\|l\|} \hline \mathrm{V}_{\mathrm{IN}}=\mathrm{V}_{\mathrm{IH}(\text { Min })} \\ \text { or } \mathrm{V}_{\mathrm{IL}(\text { Max })} \end{array}$ | Loading with $25 \Omega$ to -2.0V | (Notes 3,$4,5)$ |
|  |  | -1085 |  | mV | $-55^{\circ} \mathrm{C}$ |  |  |  |
| $\mathrm{V}_{\text {OLC }}$ | Output LOW Voltage |  | -1610 | mV | $0^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$ |  |  |  |
|  |  |  | -1555 | mV | $-55^{\circ} \mathrm{C}$ |  |  |  |
| $\mathrm{V}_{\text {OLZ }}$ | Cut-Off LOW Voltage |  | -1950 | mV | $0^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$ | $\begin{aligned} & V_{\text {IN }}=V_{I H(\text { Min }), \text { or }} \\ & V_{I L(\text { Max })} \end{aligned}$ | $\begin{aligned} & \overline{\mathrm{OEN}} \\ & =\mathrm{HIGH} \end{aligned}$ | $\begin{gathered} \text { (Notes } 3, \\ 4,5) \end{gathered}$ |
|  |  |  | -1850 |  | $-55^{\circ} \mathrm{C}$ |  |  |  |
| $\mathrm{V}_{\mathrm{IH}}$ | Input HIGH Voltage | -1165 | -870 | mV | $-55^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$ | Guaranteed HIGH signal for All inputs |  | 1, 2, 3, 4 |
| $\mathrm{V}_{\mathrm{IL}}$ | Input LOW Voltage | -1830 | -1475 | mV | $-55^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$ | Guaranteed LOW signal for All inputs |  | (Notes 3, $4,5,6)$ |
| $\mathrm{I}_{\text {IL }}$ | Input LOW Current | 0.50 |  | $\mu \mathrm{A}$ | $-55^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$ | $\begin{aligned} & \mathrm{V}_{\mathrm{EE}}=4.2 \mathrm{~V} \\ & \mathrm{~V}_{\mathrm{IN}}=\mathrm{V}_{\mathrm{IL}(\mathrm{Min})} \end{aligned}$ |  | $\begin{gathered} (\text { Notes } 3, \\ 4,5) \end{gathered}$ |
| $\mathrm{I}_{\mathrm{IH}}$ | Input HIGH Current |  | 240 | $\mu \mathrm{A}$ | $0^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$ | $\begin{aligned} & \mathrm{V}_{\mathrm{EE}}=-5.7 \mathrm{~V} \\ & \mathrm{~V}_{\mathrm{IN}}=\mathrm{V}_{\mathrm{IH}(\text { Max })} \end{aligned}$ |  | $\begin{gathered} \text { (Notes 3, } \\ 4,5) \end{gathered}$ |
|  |  |  | 340 | $\mu \mathrm{A}$ | $-55^{\circ} \mathrm{C}$ |  |  |  |
| $\mathrm{I}_{\text {EE }}$ | Power Supply Current | $\begin{aligned} & -145 \\ & -150 \end{aligned}$ | -55 | mA | $-55^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$ | Inputs Open $\begin{aligned} & \mathrm{V}_{\mathrm{EE}}=-4.2 \mathrm{~V} \text { to }-4.8 \mathrm{~V} \\ & \mathrm{~V}_{\mathrm{EE}}=-4.2 \mathrm{~V} \text { to }-5.7 \mathrm{~V} \end{aligned}$ |  | $\begin{gathered} (\text { Notes } 3, \\ 4,5) \end{gathered}$ |

Note 3: F100K 300 Series cold temperature testing is performed by temperature soaking (to guarantee junction temperature equals $-55^{\circ} \mathrm{C}$ ), then testing immediately without allowing for the junction temperature to stabilize due to heat dissipation after power-up. This provides "cold start" specs which can be considered a worst case condition at cold temperatures.

Note 4: Screen tested $100 \%$ on each device at $-55^{\circ} \mathrm{C},+25^{\circ} \mathrm{C}$, and $+125^{\circ} \mathrm{C}$, Subgroups $1,2,3,7$, and 8 .
Note 5: Sample tested (Method 5005, Table I) on each manufactured lot at $-55^{\circ} \mathrm{C},+25^{\circ} \mathrm{C}$, and $+125^{\circ} \mathrm{C}$, Subgroups A1, 2, 3, 7 , and 8 .
Note 6: Guaranteed by applying specified input condition and testing $\mathrm{V}_{\mathrm{OH}} / \mathrm{V}_{\mathrm{OL}}$.

## AC Electrical Characteristics

$\mathrm{V}_{\mathrm{EE}}=-4.2 \mathrm{~V}$ to $-5.7 \mathrm{~V}, \mathrm{~V}_{\mathrm{CC}}=\mathrm{V}_{\mathrm{CCA}}=\mathrm{GND}$

| Symbol | Parameter | $\mathrm{T}_{\mathrm{C}}=-55^{\circ} \mathrm{C}$ |  | $\mathrm{T}_{\mathrm{C}}=+25^{\circ} \mathrm{C}$ |  | $\mathrm{T}_{\mathrm{c}}+125^{\circ} \mathrm{C}$ |  | Units | Conditions | Notes |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | Min | Max | Min | Max | Min | Max |  |  |  |
| $\begin{aligned} & \hline \mathrm{t}_{\mathrm{PLH}} \\ & \mathrm{t}_{\mathrm{PHL}} \\ & \hline \end{aligned}$ | Propagation Delay Dn to Output | 0.30 | 2.60 | 0.50 | 2.40 | 0.50 | 2.70 | ns | Figures 1, 2 | $\begin{aligned} & \text { (Notes 7, } \\ & 8,10,11 \text { ) } \end{aligned}$ |
| $\mathrm{t}_{\text {PZH }}$ | Propagation Delay | 1.20 | 4.40 | 1.40 | 4.20 | 1.20 | 4.40 | ns | Figures 1, 2 | (Notes 7, |
| $\mathrm{t}_{\mathrm{PHZ}}$ | $\overline{\mathrm{OEN}}$ to Output | 0.70 | 3.00 | 0.70 | 2.80 | 0.70 | 3.20 |  |  | 8, 9, 11) |

## AC Electrical Characteristics (Continued)

$\mathrm{V}_{\mathrm{EE}}=-4.2 \mathrm{~V}$ to $-5.7 \mathrm{~V}, \mathrm{~V}_{\mathrm{CC}}=\mathrm{V}_{\mathrm{CCA}}=\mathrm{GND}$

| Symbol | Parameter | $\mathrm{T}_{\mathrm{C}}=-55^{\circ} \mathrm{C}$ |  | $\mathrm{T}_{\mathrm{C}}=+25^{\circ} \mathrm{C}$ |  | $\mathrm{T}_{\mathrm{c}}+125^{\circ} \mathrm{C}$ |  | Units | Conditions | Notes |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | Min | Max | Min | Max | Min | Max |  |  |  |
| $\begin{aligned} & \hline \mathrm{t}_{\mathrm{TLH}} \\ & \mathrm{t}_{\mathrm{THL}} \end{aligned}$ | Transition Time $20 \%$ to $80 \%, 80 \%$ to $20 \%$ | 0.40 | 2.50 | 0.40 | 2.40 | 0.40 | 2.70 | ns | Figures 1, 2 | (Note 10) |

Note 7: F100K 300 Series cold temperature testing is performed by temperature soaking (to guarantee junction temperature equals $-55^{\circ} \mathrm{C}$ ), then testing immediately after power-up. This provides "cold start" specs which can be considered a worst case condition at cold temperatures.
Note 8: Screen tested $100 \%$ on each device at $+25^{\circ} \mathrm{C}$ temperature only, Subgroup A9.
Note 9: Sample tested (Method 5005, Table I) on each manufactured lot at $+25^{\circ} \mathrm{C}$, Subgroup A9, and at $+125^{\circ} \mathrm{C}$ and $-55^{\circ} \mathrm{C}$ temperatures, Subgroups A10 and A11.
Note 10: Not tested at $+25^{\circ} \mathrm{C},+125^{\circ} \mathrm{C}$, and $-55^{\circ} \mathrm{C}$ temperature (design characterization data).
Note 11: The propagation delay specified is for single output switching. Delays may vary up to 300 ps with multiple outputs switching.

## Test Circuitry



## Notes:

$\mathrm{V}_{\mathrm{CC}}, \mathrm{V}_{\mathrm{CCA}}=+2 \mathrm{~V}, \mathrm{~V}_{\mathrm{EE}}=-2.5 \mathrm{~V}$
$L 1$ and $L 2=$ equal length $50 \Omega$ impedance lines
$R_{T}=50 \Omega$ terminator internal to scope
Decoupling $0.1 \mu \mathrm{~F}$ from GND to $\mathrm{V}_{\mathrm{CC}}$ and $\mathrm{V}_{\mathrm{EE}}$
All unused outputs are loaded with $25 \Omega$ to GND
$\mathrm{C}_{\mathrm{L}}=$ Fixture and stray capacitance $\leq 3 \mathrm{pF}$
FIGURE 1. AC Test Circuit

## Switching Waveforms



Note:
The output AC measurement point for cut-off propagation delay
testing $=$ the $50 \%$ voltage point between active $\mathrm{V}_{\mathrm{OL}}$ and $\mathrm{V}_{\mathrm{OH}}$.
FIGURE 2. Propagation Delay, Cut-Off and Transition Times
$\square$

Physical Dimensions inches (millimeters) unless otherwise noted


24-Lead Ceramic Dual-In-Line Package (0.400" Wide) (D) NS Package Number J24E


W24B (REV D)
24-Lead Quad Cerpak (F)
NS Package Number W24B

\begin{abstract}
100352 Low Power 8-Bit Buffer with Cut-Off Drivers

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